

ABSTRACT OF THE DISCLOSURE

An apparatus for bonding disc substrates is provided with a spinner which spreads adhesive placed between a first substrate and second substrate, and a curing device which radiates ultraviolet light onto the adhesive through the substrate to cure it. The curing device includes; a support mechanism which supports the first substrate and second substrate after the adhesive is spread by the spinner, a semiconductor light emitting apparatus having a plurality of light emitting semiconductor elements arranged facing a region where the adhesive is cured, and a positioning mechanism which positions the semiconductor light emitting apparatus such that the light emitting semiconductor elements are a predetermined distance away from the adhesive. The adhesive is cured or semi-cured by ultraviolet light emitted from the plurality of light emitting semiconductor elements.